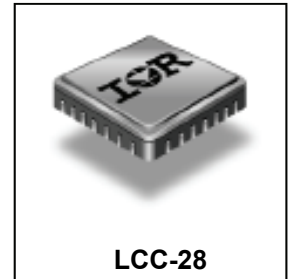


**RADIATION HARDENED
POWER MOSFET
SURFACE MOUNT (LCC-28)**

**100V, QUAD N CHANNEL
RAD-Hard HEXFET TECHNOLOGY**

Product Summary

Part Number	Radiation Level	RDS(on)	I _D
IRHQ7110	100 kRads(Si)	0.6Ω	3.0A
IRHQ3110	300 kRads(Si)	0.75Ω	3.0A
IRHQ5110	500 kRads(Si)	0.75Ω	3.0A
IRHQ8110	1000 kRads(Si)	0.75Ω	3.0A



Description

IRHQ7110 is part of International Rectifier HiRel family of products. IR HiRel RAD-Hard HEXFET technology provides high performance power MOSFETs for space applications. This technology has over a decade of proven performance and reliability in satellite applications. These devices have been characterized for both Total Dose and Single Event Effects (SEE). The combination of low R_{ds(on)} and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

Features

- Single Event Effect (SEE) Hardened
- Low RDS(on)
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Ceramic Package
- Surface Mount
- Light Weight
- ESD Rating: Class 1A per MIL-STD-750, Method 1020

Absolute Maximum Ratings for Each N-Channel Device

Pre-Irradiation

	Parameter		Units
I _D @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	3.0	A
I _D @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	1.9	
I _{DM}	Pulsed Drain Current ①	12	
P _D @ T _C = 25°C	Maximum Power Dissipation	12	W
	Linear Derating Factor	0.01	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②	85	mJ
I _{AR}	Avalanche Current ①	3.0	A
E _{AR}	Repetitive Avalanche Energy ①	1.2	mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.0	V/ns
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Package Mounting Surface Temperature	300 (for 5s)	
	Weight	0.89 (Typical)	

For Footnotes, refer to the page 2

Electrical Characteristics for Each N-Channel Device @ T_J = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V _{GS} = 0V, I _D = 1.0mA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	0.11	—	V/°C	Reference to 25°C, I _D = 1.0mA
R _{DS(on)}	Static Drain-to-Source On-State Resistance	—	—	0.6	Ω	V _{GS} = 12V, I _D = 1.9A ④
V _{GS(th)}	Gate Threshold Voltage	2.0	—	4.0	V	V _{DS} = V _{GS} , I _D = 1.0mA
G _{fs}	Forward Transconductance	1.4	—	—	S	V _{DS} = 15V, I _D = 1.9A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	25	μA	V _{DS} = 80V, V _{GS} = 0V
		—	—	250		V _{DS} = 80V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Q _G	Total Gate Charge	—	—	11	nC	I _D = 3.0A
Q _{GS}	Gate-to-Source Charge	—	—	4.0		V _{DS} = 50V
Q _{GD}	Gate-to-Drain ('Miller') Charge	—	—	5.5		V _{GS} = 12V
t _{d(on)}	Turn-On Delay Time	—	—	20	ns	V _{DD} = 50V
t _r	Rise Time	—	—	25		I _D = 3.0A
t _{d(off)}	Turn-Off Delay Time	—	—	40		R _G = 7.5Ω
t _f	Fall Time	—	—	40		V _{GS} = 12V
L _S + L _D	Total Inductance	—	6.1	—	nH	Measured from center of Drain pad to center of Source pad
C _{iss}	Input Capacitance	—	270	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	110	—		V _{DS} = 25V
C _{rss}	Reverse Transfer Capacitance	—	23	—		f = 1.0MHz

Source-Drain Diode Ratings and Characteristics for Each N-Channel Device

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	3.0	A	
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	12		
V _{SD}	Diode Forward Voltage	—	—	1.2	V	T _J = 25°C, I _S = 3.0A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	173	ns	T _J = 25°C, I _F = 3.0A, V _{DD} ≤ 25V
Q _{rr}	Reverse Recovery Charge	—	—	863	nC	di/dt = 100A/μs ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Thermal Resistance for Each N-Channel Device

	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	—	10.4	°C/W

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② V_{DD} = 25V, starting T_J = 25°C, L = 18.7mH, Peak I_L = 3.0A, V_{GS} = 12V
- ③ I_{SD} ≤ 3.0A, di/dt ≤ 165A/μs, V_{DD} ≤ 100V, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ **Total Dose Irradiation with V_{GS} Bias.** 12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.** 80volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.

Radiation Characteristics

IR HiRel Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at IR HiRel is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table1. Electrical Characteristics for Each N-Ch. Dev.@ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

	Parameter	100 kRads (Si) ¹		300k to 1000kRads (Si) ²		Units	Test Conditions
		Min.	Max.	Min.	Max.		
BV_{DSS}	Drain-to-Source Breakdown Voltage	100	—	100	—	V	$V_{GS} = 0V, I_D = 1.0mA$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.0	2.0	4.0	V	$V_{DS} = V_{GS}, I_D = 1.0mA$
I_{GSS}	Gate-to-Source Leakage Forward	—	100	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100	—	-100	nA	$V_{GS} = -20V$
I_{DSS}	Zero Gate Voltage Drain Current	—	10	—	10	μA	$V_{DS} = 80V, V_{GS} = 0V$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.556	—	0.706	Ω	$V_{GS} = 12V, I_D = 1.9A$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (LCC-28)	—	0.6	—	0.75	Ω	$V_{GS} = 12V, I_D = 1.9A$
V_{SD}	Diode Forward Voltage ④	—	1.2	—	1.2	V	$V_{GS} = 0V, I_D = 3.0A$

1. Part number IRHQ7110
2. Part numbers IRHQ3110, IRHQ5110, IRHQ8110

IR HiRel radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

Ion	LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)				
				@VGS=0V	@VGS=-5V	@VGS=-10V	@VGS=-15V	@VGS=-20V
Cu	28	285	43	100	100	100	80	60
Br	36.8	305	39	100	90	70	50	—
I	59.8	343	32.6	50	40	35	—	—

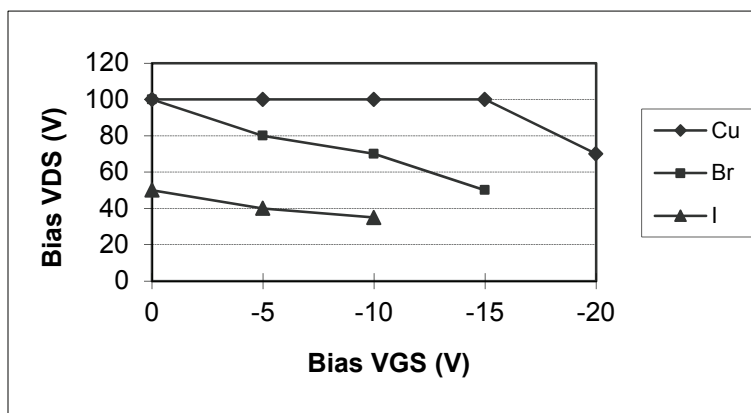


Fig a. Typical Single Event Effect, Safe Operating Area

For Footnotes, refer to the page 2

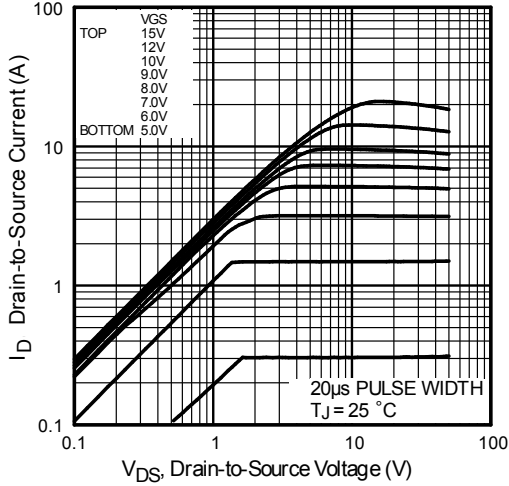


Fig 1. Typical Output Characteristics

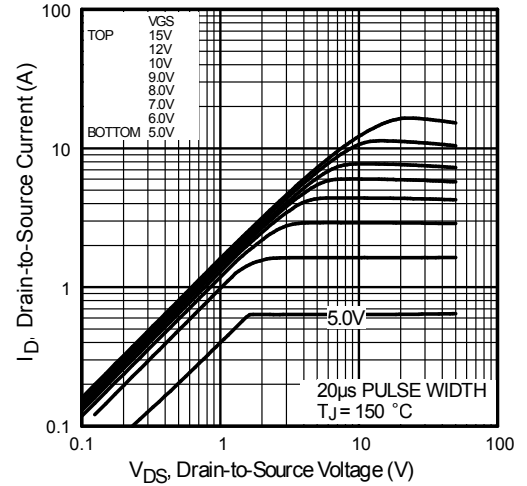


Fig 2. Typical Output Characteristics

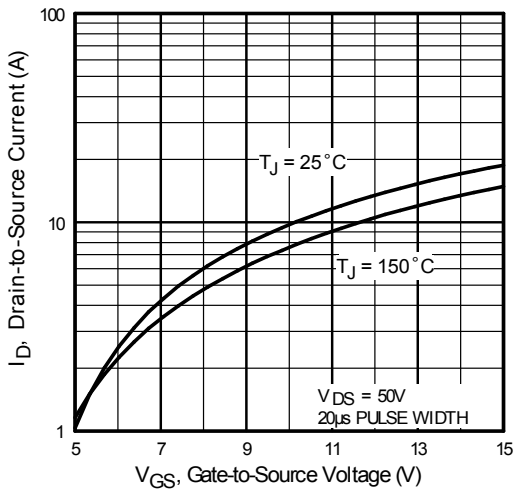


Fig 3. Typical Transfer Characteristics

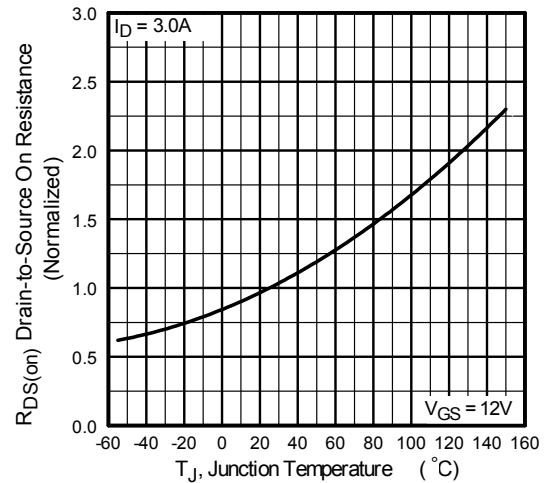


Fig 4. Normalized On-Resistance Vs. Temperature

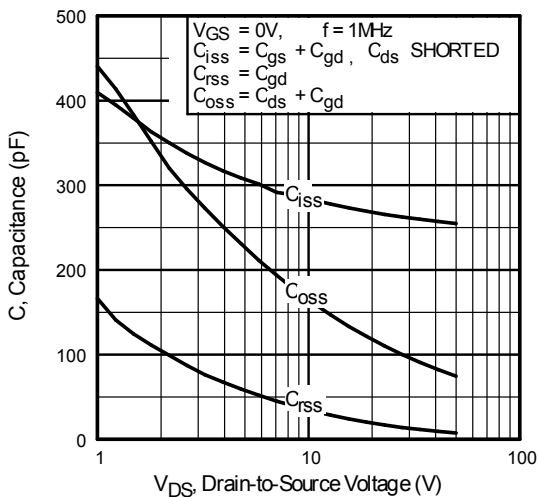


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

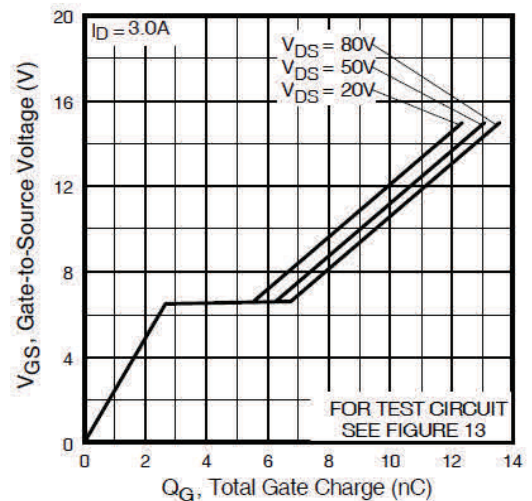


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

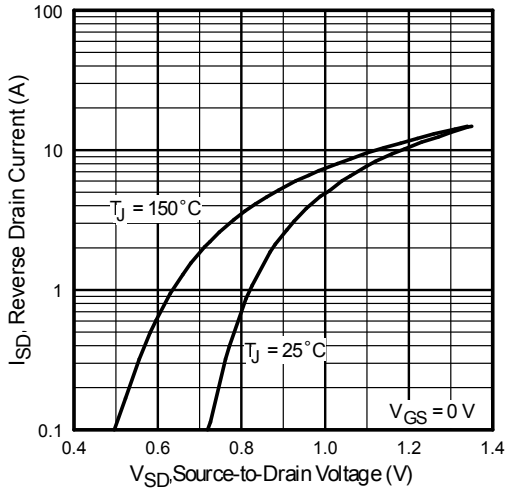


Fig 7. Typical Source-Drain Diode Forward Voltage

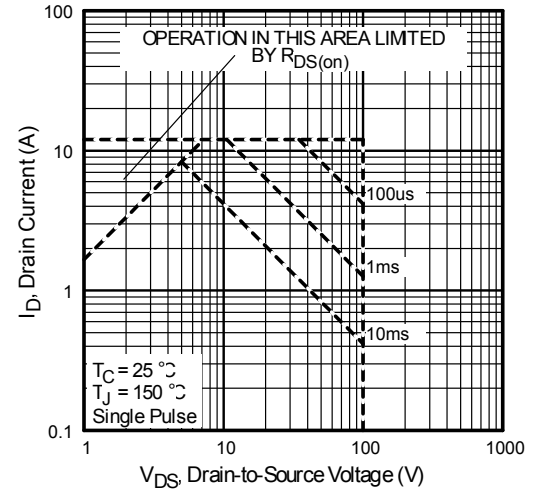


Fig 8. Maximum Safe Operating Area

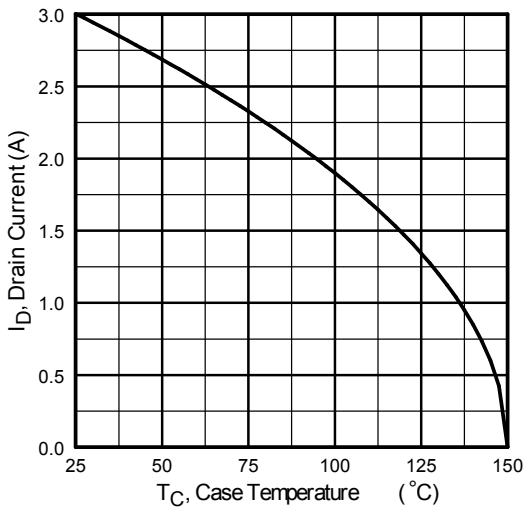


Fig 9. Maximum Drain Current Vs. Case Temperature

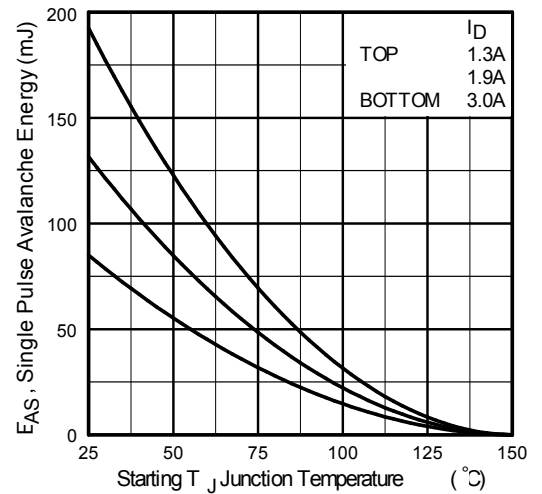


Fig 10. Maximum Avalanche Energy Vs. Drain Current

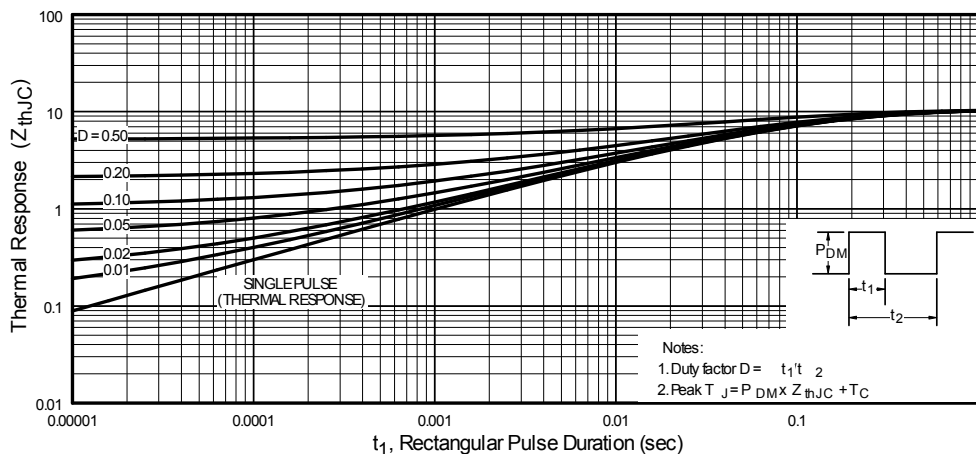


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

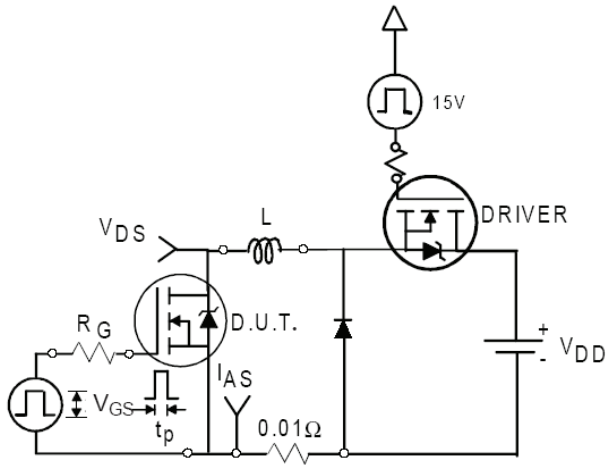


Fig 12a. Unclamped Inductive Test Circuit

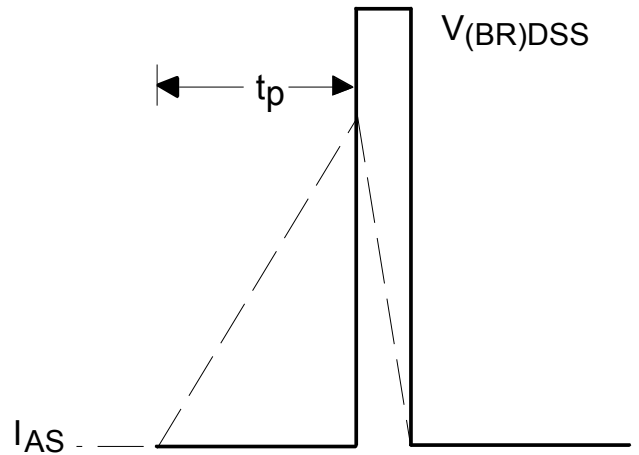


Fig 12b. Unclamped Inductive Waveforms

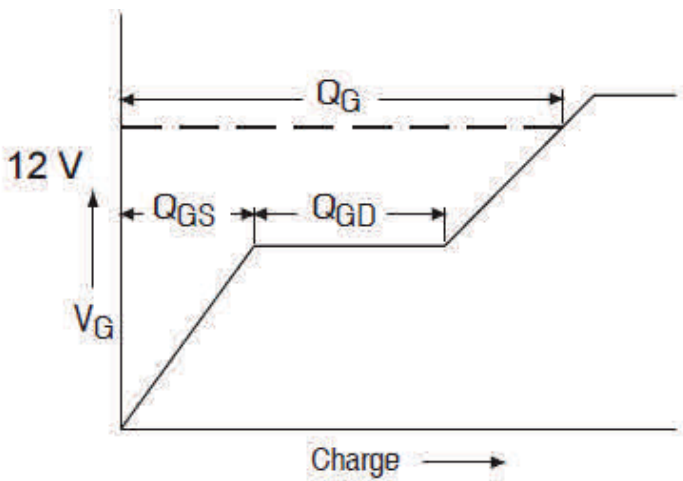


Fig 13a. Gate Charge Waveform

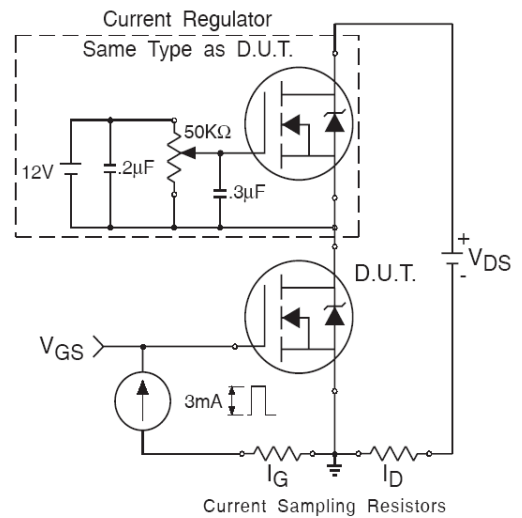


Fig 13b. Gate Charge Test Circuit

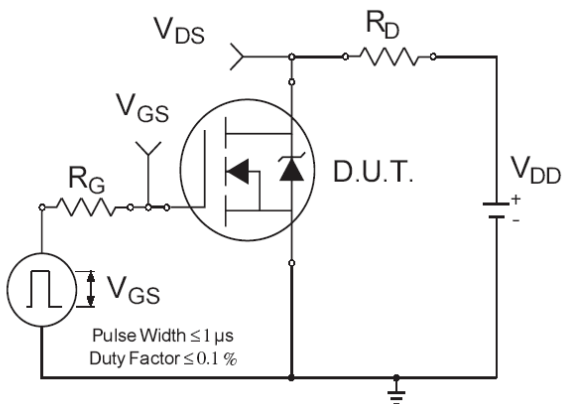


Fig 14a. Switching Time Test Circuit

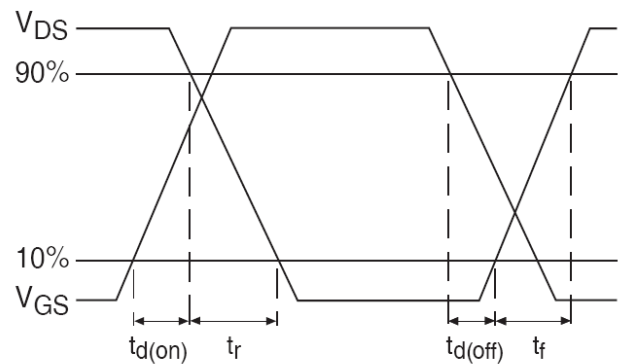
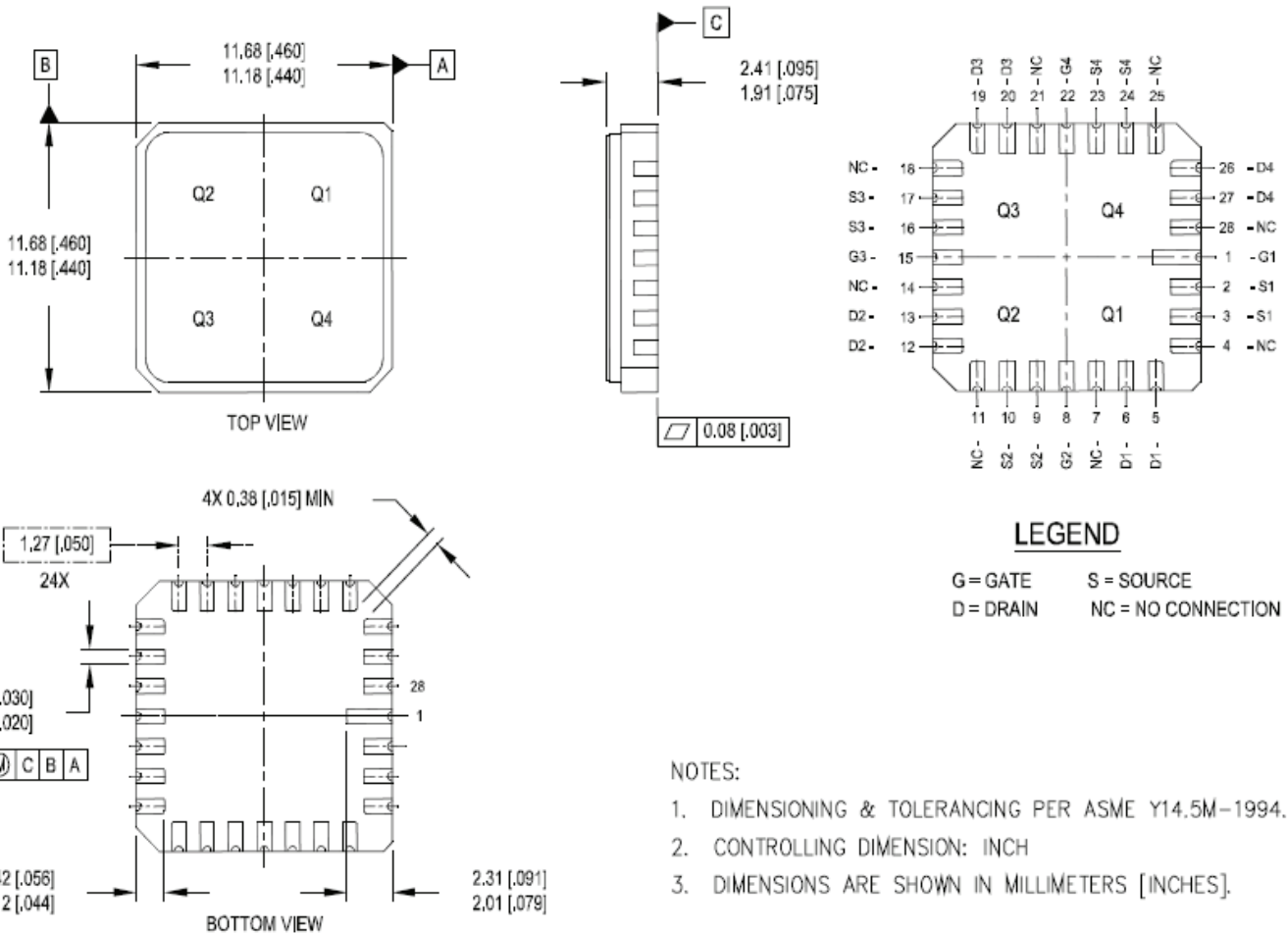


Fig 14b. Switching Time Waveforms

Case Outline and Dimensions —LCC-28



IMPORTANT NOTICE

The information given in this document shall be in no event regarded as guarantee of conditions or characteristic. The data contained herein is a characterization of the component based on internal standards and is intended to demonstrate and provide guidance for typical part performance. It will require further evaluation, qualification and analysis to determine suitability in the application environment to confirm compliance to your system requirements.

With respect to any example hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind including without limitation warranties on non- infringement of intellectual property rights and any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's product and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of any customer's technical departments to evaluate the suitability of the product for the intended applications and the completeness of the product information given in this document with respect to applications.

For further information on the product, technology, delivery terms and conditions and prices, please contact your local sales representative or go to (www.infineon.com/hirel).

WARNING

Due to technical requirements products may contain dangerous substances. For information on the types in question, please contact your nearest Infineon Technologies office.